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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#10
K Cooper
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In re patent application of

Applicant: Yoshimasa KAWASE

Title: WAFER HEAT-TREATMENT SYSTEM AND WAFER HEAT-TREATMENT METHOD

Appl. No.: 10/066,783

Filing Date: February 6, 2002

Examiner: G. Wilson

Art Unit: 3749

REPLY UNDER 37 C.F.R. § 1.111

Mail Stop NON-FEE AMENDMENT
Commissioner for Patents
PO Box 1450
Alexandria, Virginia 22313-1450

Sir:

This communication is responsive to the Non-Final Office Action dated April 8, 2003, concerning the above-referenced patent application.

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